

**Amendments to the Specification:**

Please replace the paragraph beginning on page 24, line 14 with the following amended paragraph:

Since the surface acoustic wave devices 501 in the present embodiment are surrounded by the thermosetting resin composition 508 as described above, it is preferable to provide the functional portion with a space holding structure so that the functional portion of the surface acoustic wave device 501 does not contact this resin composition 508. This allows the resin to be filled also between the surface acoustic wave devices ~~[[508]]~~ 501 and the circuit board 507, and thus an external force applied during a subsequent grinding or abrading process for reducing thickness can be supported not only by the metal bumps 505 but by the filled resin. As a result, stress is not concentrated in the vicinity of the metal bumps 505, thus preventing problems such as breakage of the piezoelectric substrate 502.